

1 ~~42~~ 74.(NEW) A polishing apparatus according to claim 73, wherein said polishing pressure comprises a fluid pressure. 41

~~43~~ 75.(NEW) A polishing apparatus according to claim 73, wherein said polishing pressure comprises a compressed air pressure. 41

~~41~~ 76.(NEW) A polishing apparatus comprising to claim 73, wherein said central area and said outer circumferential area are formed by chambers formed in said top ring. 41

B1 cont. ~~45~~ 77.(NEW) A polishing apparatus according to claim 73, further comprising:
a third area located between said central area and said outer circumferential area. 41

~~44~~ 78.(NEW) A polishing apparatus according to claim 73, further comprising:
a presser ring disposed around the workpiece and contacting a polishing surface for polishing the workpiece. 41

~~47~~ 79.(NEW) A polishing apparatus according to claim 78, wherein said presser ring is pressed by pressurized fluid. 46

Sub 50

80.(NEW) A method for polishing a workpiece, comprising:
holding a workpiece on a surface of a top ring; and
applying a polishing pressure on a surface of the workpiece, wherein
an area where said polishing pressure is applied is divided to a central area and an outer
circumferential area of the workpiece, and the radial width of said outer circumferential
area is narrower than that of said central area.

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49 81.(NEW) A method according to claim ~~80~~, wherein said polishing pressure
comprises a fluid pressure.

B1 Cont

50 82.(NEW) A method according to claim ~~80~~, wherein said polishing pressure
comprises a compressed air pressure.

51 83.(NEW) A method according to claim ~~80~~, wherein said central area and said
outer circumferential area are formed by chambers formed in said top ring.

52 84.(NEW) A method according to claim ~~80~~, wherein the area where said
polishing pressure is applied is divided to said central area, said outer circumferential area
and a third area located between said central area and said outer circumferential area.

53 85.(NEW) A method according to claim ~~80~~, further comprising:

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pressing a presser ring disposed around the workpiece against a polishing surface for polishing the workpiece.

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~~86.(NEW)~~ 53 A method according to claim 85, wherein said presser ring is pressed by pressurized fluid.

END

87.(NEW) A polishing apparatus for polishing a surface of a workpiece, comprising:
a turntable having a polishing surface thereon;
a top ring to support the workpiece to be polished on a holding surface of said top ring;
a presser ring vertically movably disposed around said top ring;
a mechanism to move said top ring vertically so that said top ring moves toward and away from said polishing surface;
a pressing mechanism to provide a first pressing force onto the workpiece, said first pressing force being different in a central portion and an outer circumferential portion of the workpiece; and
a pressing device to press said presser ring against said polishing surface under a second pressing force, said second pressing force being independently controllable with respect to said first pressing force.

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